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ARTERIS COLLABORATES ON INTERPOSER TEST CHIP PROJECTS WITH TSMC

Goal is more efficient and timely commercialization of Through-Silicon Via (TSV) technology using Arteris Network-on-Chip (NoC) interconnect IP & Tool products

SUNNYVALE, California – December 6, 2011 – Arteris Inc., the inventor and leading supplier of network-on-chip (NoC) interconnect IP solutions, today announced that it is collaborating with TSMC by incorporating Arteris’ FlexNoC Network–on-Chip (NoC) interconnect IP into an SoC die on silicon interposer test chip.

“TSMC chose to work with Arteris on the interposer based test chip program because its interconnect technology is ideally suited to addressing the SoC wire routing congestion and timing closure challenges,” said Suk Lee, Director of Design Infrastructure Marketing at TSMC. “TSMC and Arteris are working together to make it easier for our joint customers to adopt these technologies.”

In addition to working together on the interposer based test chip program, Arteris is a TSMC Open Innovation Platform Partner and a participant in TSMC’s Reference Flows 11.0 and 12.0.

Unlike other interconnect solutions, Arteris’s FlexNoC network on chip interconnect IP is physically implemented as a distributed network of small design elements within a SoC floorplan. Furthermore, FlexNoC’s flexibility simultaneously addresses bandwidth, latency and quality of service (QoS) requirements introduced with wide data paths.

“TSMC and Arteris are working together to accelerate adoption of interconnect fabric technology by increasing design efficiency and proactively addressing the routing congestion and timing closure issues,” said Charlie Janac, Arteris President and CEO.

About Arteris

Arteris, Inc. provides Network-on-Chip interconnect IP and tools to accelerate System-on-Chip semiconductor (SoC) assembly for a wide range of applications. Results obtained by using the Arteris product line include lower power, higher performance, more efficient design reuse and faster development of ICs, SoCs and FPGAs.

Founded by networking experts, Arteris operates globally with headquarters in Sunnyvale, California and an engineering center in Paris, France. Arteris is a private company backed by a group of international investors including ARM Holdings, Crescendo Ventures, DoCoMo Capital, Qualcomm Incorporated, Synopsys, TVM Capital, and Ventech. More information can be found at www.arteris.com.

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